



Layer	Base CU / Plt	Thick	Type	Stackup	Subs	Imp	Material	Dk	Df
Silkscreen		0.00					Taiyo-SS - White		
Soldermask		0.60					Taiyo-SM - Green	2.70	0.033
Lyr1	0.5oz / Std	1.80	S						
Prepreg		7.64					370HR - 2x2113	3.99	0.022
Lyr2	1oz	1.20	P						
Core		14.00					370HR - 14.0mils	4.74	0.021
Lyr3	1oz	1.20	S						
Prepreg		9.08					370HR - 2x2113/1x1080	3.95	0.023
Lyr4	1oz	1.20	S						
Core		14.00					370HR - 14.0mils	4.74	0.021
Lyr5	1oz	1.20	P						
Prepreg		7.64					370HR - 2x2113	3.99	0.022
Lyr6	0.5oz / Std	1.80	S						
Soldermask		0.60					Taiyo-SM - Green	2.70	0.033
Silkscreen		0.00					Taiyo-SS - White		

Required Thickness

Type	Req. Thick	Tol% +	Tol% -	Act. Thick	Measured
Overall	62.0	10.0	10.0	62.0	
Over lamination	58.4	10.0	10.0	58.4	
Over laminate	57.2	10.0	10.0	57.2	
Over metal	60.8	10.0	10.0	60.8	

Bill of Materials

Material	Qty/Panel	Total Qty
14.0mils 1/1 core	2	2
0.5oz foil	2	2
2113 prepreg	6	6
1080 prepreg	1	1
White silkscreen	2	2
	13	13

Comments